

SWITCHMODE™ Series PNP Silicon Power Transistors

The MJE5850, MJE5851 and the MJE5852 transistors are designed for high-voltage, high-speed, power switching in inductive circuits where fall time is critical. They are particularly suited for line operated SWITCHMODE applications such as:

- Switching Regulators
- Inverters
- Solenoid and Relay Drivers
- Motor Controls
- Deflection Circuits

Fast Turn-Off Times

100 ns Inductive Fall Time @ 25°C (Typ) 125 ns Inductive Crossover Time @ 25°C (Typ)

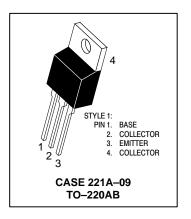
Operating Temperature Range -65 to +150°C

100°C Performance Specified for:

Reversed Biased SOA with Inductive Loads Switching Times with Inductive Loads Saturation Voltages Leakage Currents



8 AMPERE PNP SILICON POWER TRANSISTORS 300, 350, 400 VOLTS 80 WATTS



MAXIMUM RATINGS

Rating	Symbol	MJE5850	MJE5851	MJE5852	Unit
Collector–Emitter Voltage	VCEO(sus)	300	350	400	Vdc
Collector–Emitter Voltage	VCEV	350 400 450		450	Vdc
Emitter Base Voltage	V _{EB}	6.0		Vdc	
Collector Current — Continuous Peak (1)	I _C	8.0 1 6			Adc
Base Current — Continuous Peak (1)	I _B	4.0 8.0			Adc
Total Power Dissipation @ T _C = 25°C Derate above 25°C	PD	80		Watts	
Derate above 25°C		0.640		W/°C	
Operating and Storage Junction Temperature Range	T _J , T _{Stg}	-65 to 150			°C

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction to Case	$R_{ heta}$ JC	1.25	°C/W
Maximum Lead Temperature for Soldering Purposes: 1/8" from Case for 5 Seconds	TL	275	°C

(1) Pulse Test: Pulse Width = 5 ms, Duty Cycle \leq 10%.

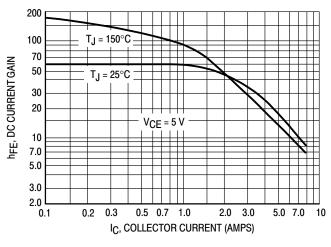
Preferred devices are ON Semiconductor recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS (T_C = 25°C unless otherwise noted)

	Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Collector–Emitter Sustain (I _C = 10 mA, I _B = 0)	M	IJE5850 IJE5851 IJE5852	VCEO(sus)	300 350 400	_	<u> </u>	Vdc
Collector Cutoff Current (VCEV = Rated Value, VBE(off) = 1.5 Vdc) (VCEV = Rated Value, VBE(off) = 1.5 Vdc, TC = 100°C)		ICEV	=	_	0.5 2.5	mAdc	
Collector Cutoff Current (VCE = Rated VCEV, RBE = 50 Ω, TC = 100°C)			ICER	_	_	3.0	mAdc
Emitter Cutoff Current (V _{EB} = 6.0 Vdc, I _C = 0))		I _{EBO}	_	_	1.0	mAdc
SECOND BREAKDOWN							1
Second Breakdown Colle	Second Breakdown Collector Current with base forward biased		I _{S/b}	See Figure 12			
Clamped Inductive SOA	with base reverse biased		RBSOA		See Figure 13		
*ON CHARACTERISTICS		l.					
DC Current Gain (I _C = 2.0 Adc, V _{CE} = 5 Vdc) (I _C = 5.0 Adc, V _{CE} = 5 Vdc)			hFE	15 5		_ _	_
Collector–Emitter Saturation Voltage ($I_C = 4.0$ Adc, $I_B = 1.0$ Adc) ($I_C = 8.0$ Adc, $I_B = 3.0$ Adc) ($I_C = 4.0$ Adc, $I_B = 1.0$ Adc, $I_C = 100^{\circ}$ C)			VCE(sat)	_ _ _	_ _ _	2.0 5.0 2.5	Vdc
Base–Emitter Saturation Voltage (I_C = 4.0 Adc, I_B = 1.0 Adc) (I_C = 4.0 Adc, I_B = 1.0 Adc, T_C = 100°C)		VBE(sat)	_	_	1.5 1.5	Vdc	
DYNAMIC CHARACTERIS	STICS						
Output Capacitance (VCB = 10 Vdc, I _E = 0, f _{test} = 1.0 kHz)		C _{ob}	_	270	_	pF	
SWITCHING CHARACTE	RISTICS						
Resistive Load (Table 1)						
Delay Time	(V _{CC} = 250 Vdc, I _C = 4.0 A, I _{B1} = 1.0 A	٦,	t _d	_	0.025	0.1	μs
Rise Time	$t_p = 50 \mu s$, Duty Cycle $\leq 2\%$)	-	t _r	_	0.100	0.5	μs
Storage Time	(V _{CC} = 250 Vdc, I _C = 4.0 A, I _{B1} = 1.0 A	٦,	t _S	_	0.60	2.0	μs
Fall Time	$V_{BE(off)} = 5 \text{ Vdc}, t_p = 50 \mu\text{s}, \text{ Duty Cycle} \le 2\%$		t _f	_	0.11	0.5	μs
Inductive Load, Clampe	ed (Table 1)						
Storage Time			t _{SV}	_	0.8	3.0	μs
Crossover Time	(I _{CM} = 4 A, V _{CEM} = 250 V, I _{B1} = 1.0 A V _{BE(off)} = 5 Vdc, T _C = 100°C)	,	t _C	_	0.4	1.5	μs
Fall Time	BE(OII) - 12-5, 10 100 07	ļ	t _{fi}	_	0.1	_	μs
Storage Time			t _{SV}	_	0.5	_	μs
Crossover Time	(I _{CM} = 4 A, V _{CEM} = 250 V, I _{B1} = 1.0 A V _{BE(off)} = 5 Vdc, T _C = 25°C)	,	t _C	_	0.125	_	μs
Fall Time	DE(011)	•	t _{fi}	_	0.1	_	μs

^{*}Pulse Test: PW = 300 μs. Duty Cycle ≤ 2%

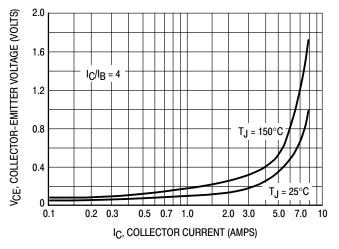
TYPICAL ELECTRICAL CHARACTERISTICS



2.0 1.6 1.6 1.0 A 2.5 A 5.0 A T J = 25°C 1.0 A 0.0 1 0.02 0.05 0.1 0.2 0.5 1.0 2.0 5.0 10 IB, BASE CURRENT (AMPS)

Figure 1. DC Current Gain

Figure 2. Collector Saturation Region



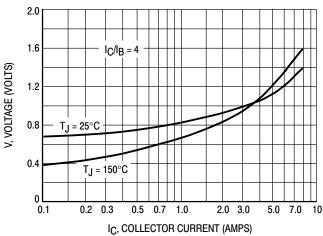
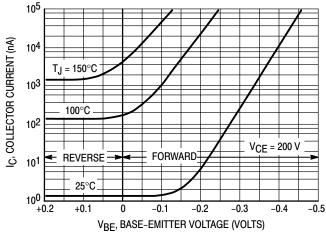


Figure 3. Collector-Emitter Saturation Voltage

Figure 4. Base-Emitter Voltage



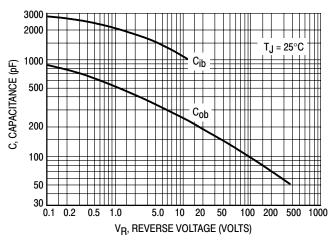
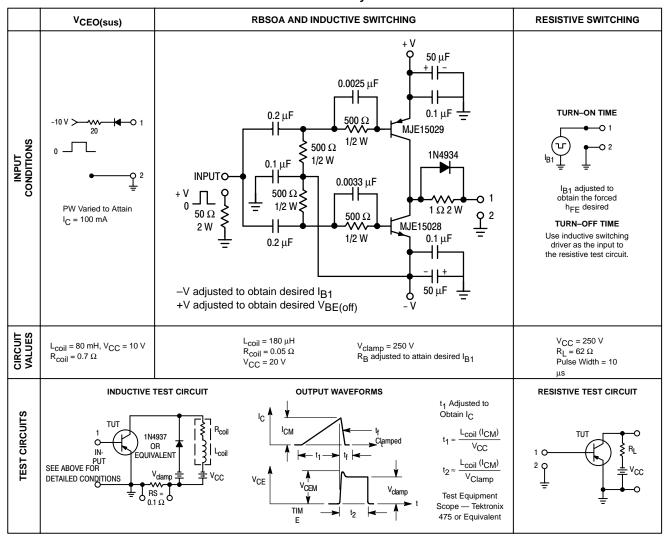


Figure 5. Collector Cutoff Region

Figure 6. Capacitance

Table 1. Test Conditions for Dynamic Performance



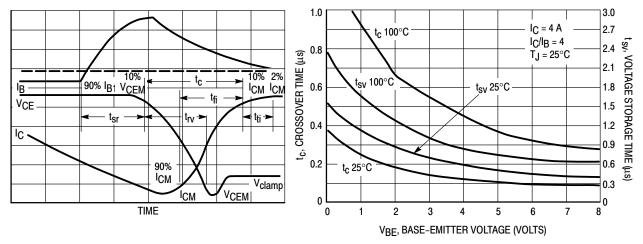


Figure 7. Inductive Switching Measurements

Figure 8. Inductive Switching Times

SWITCHING TIMES NOTE

In resistive switching circuits, rise, fall, and storage times have been defined and apply to both current and voltage waveforms since they are in phase. However, for inductive loads which are common to SWITCHMODE power supplies and hammer drivers, current and voltage waveforms are not in phase. Therefore, separate measurements must be made on each waveform to determine the total switching time. For this reason, the following new terms have been defined.

t_{SV} = Voltage Storage Time, 90% I_{B1} to 10% V_{CEM}

 t_{rv} = Voltage Rise Time, 10–90% V_{CEM}

 t_{fi} = Current Fall Time, 90–10% I_{CM}

 t_{ti} = Current Tail, 10–2% I_{CM}

 t_c = Crossover Time, 10% V_{CEM} to 10% I_{CM}

An enlarged portion of the inductive switching waveform is shown in Figure 7 to aid on the visual identity of these terms.

For the designer, there is minimal switching loss during storage time and the predominant switching power losses occur during the crossover interval and can be obtained using the standard equation from AN–222A:

 $PSWT = 1/2 \ VCCIC(t_c)f$

In general, $t_{rv} + t_{fi} \approx t_c$. However, at lower test currents this relationship may not be valid.

As is common with most switching transistors, resistive switching is specified at 25°C and has become a benchmark for designers. However, for designers of high frequency converter circuits, the user oriented specifications which make this a "SWITCHMODE" transistor are the inductive switching speeds (t_c and t_{sv}) which are guaranteed at 100°C.

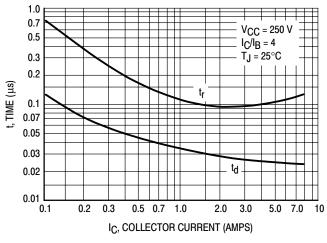


Figure 9. Turn-On Switching Times

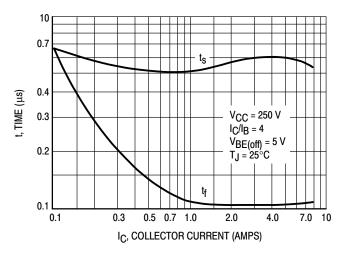


Figure 10. Turn-Off Switching Time

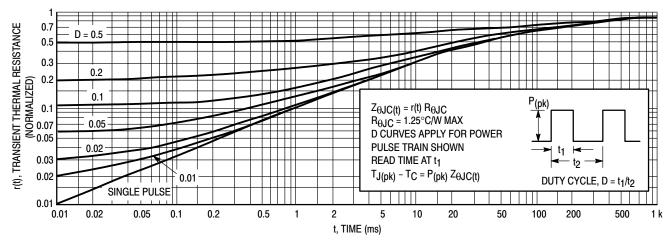


Figure 11. Typical Thermal Response [Z_HJC(t)]

The Safe Operating Area figures shown in Figures 12 and 13 are specified for these devices under the test conditions shown.

100 us IC, COLLECTOR CURRENT (AMPS) 5.0 2.0 T_C = 1.0 0.5 BONDING WIRE LIMIT 0.2 THERMAL LIMIT (SINGLE PULSE) SECOND BREAKDOWN LIMI 0.05 MJE5850 MJE5851 MJE5852 0.02 7.0 10 20 40 70 300 400 500 100 200 VCF, COLLECTOR-EMITTER VOLTAGE (VOLTS)

Figure 12. Maximum Forward Bias Safe Operating Area

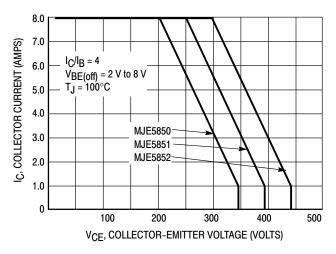


Figure 13. RBSOA, Maximum Reverse Bias Safe Operating Area

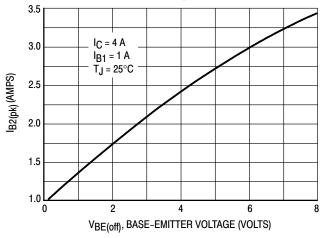


Figure 14. Peak Reverse Base Current

SAFE OPERATING AREA INFORMATION

FORWARD BIAS

There are two limitations on the power handling ability of a transistor average junction temperature and second breakdown. Safe operating area curves indicate $I_C - V_{CE}$ limits of the transistor that must be observed for reliable operation, i.e., the transistor must not be subjected to greater dissipation than the curves indicate.

The data of Figure 12 is based on $T_C = 25^{\circ}C$; $T_{J(pk)}$ is variable depending on power level. Second breakdown pulse limits are valid for duty cycles to 10% but must be derated when $T_C \ge 25^{\circ}C$. Second breakdown limitations do not derate the same as thermal limitations. Allowable current at the voltages shown on Figure 12 may be found at any case temperature by using the appropriate curve on Figure 15.

 $T_{J(pk)}$ may be calculated from the data in Figure 11. At high case temperatures, thermal limitations will reduce the power that can be handled to values less than the limitations imposed by second breakdown.

REVERSE BIAS

For inductive loads, high voltage and high current must be sustained simultaneously during turn-off, in most cases, with the base to emitter junction reverse biased. Under these conditions the collector voltage must be held to a safe level at or below a specific value of collector current. This can be accomplished by several means such as active clamping, RC snubbing, load line shaping, etc. The safe level for these devices is specified as Reverse Bias Safe Operating Area and represents the voltage-current condition allowable during reverse biased turn-off. This rating is verified under clamped conditions so that the device is never subjected to an avalanche mode. Figure 13 gives the RBSOA characteristics.

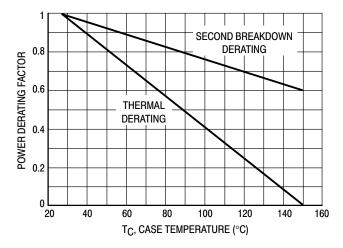
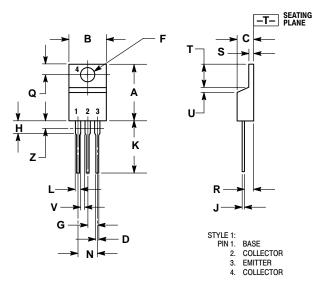


Figure 15. Forward Bias Power Derating

PACKAGE DIMENSIONS

TO-220AA **CASE 221A-09 ISSUE AA**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Н	0.110	0.155	2.80	3.93	
J	0.018	0.025	0.46	0.64	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
N	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Z		0.080		2.04	

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